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**Supplementary information**

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**Highly active and stable stepped Cu surface  
for enhanced electrochemical CO<sub>2</sub>  
reduction to C<sub>2</sub>H<sub>4</sub>**

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Supplementary Information for

## Highly active and stable stepped Cu surface for enhanced electrochemical CO<sub>2</sub> reduction to C<sub>2</sub>H<sub>4</sub>.

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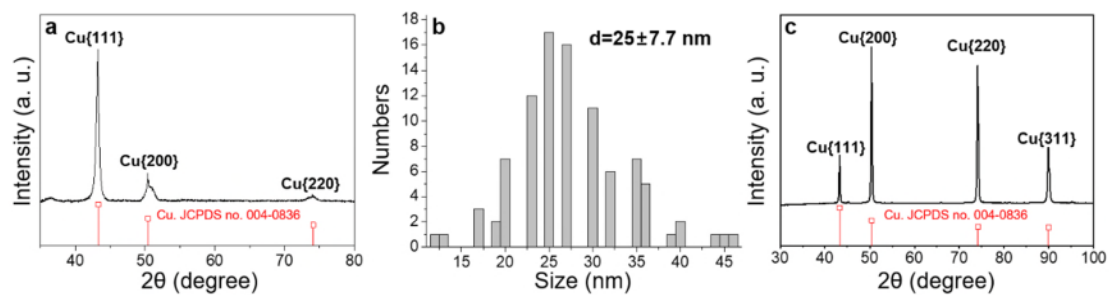
This PDF file includes:

Supplementary Figures 1 to 15

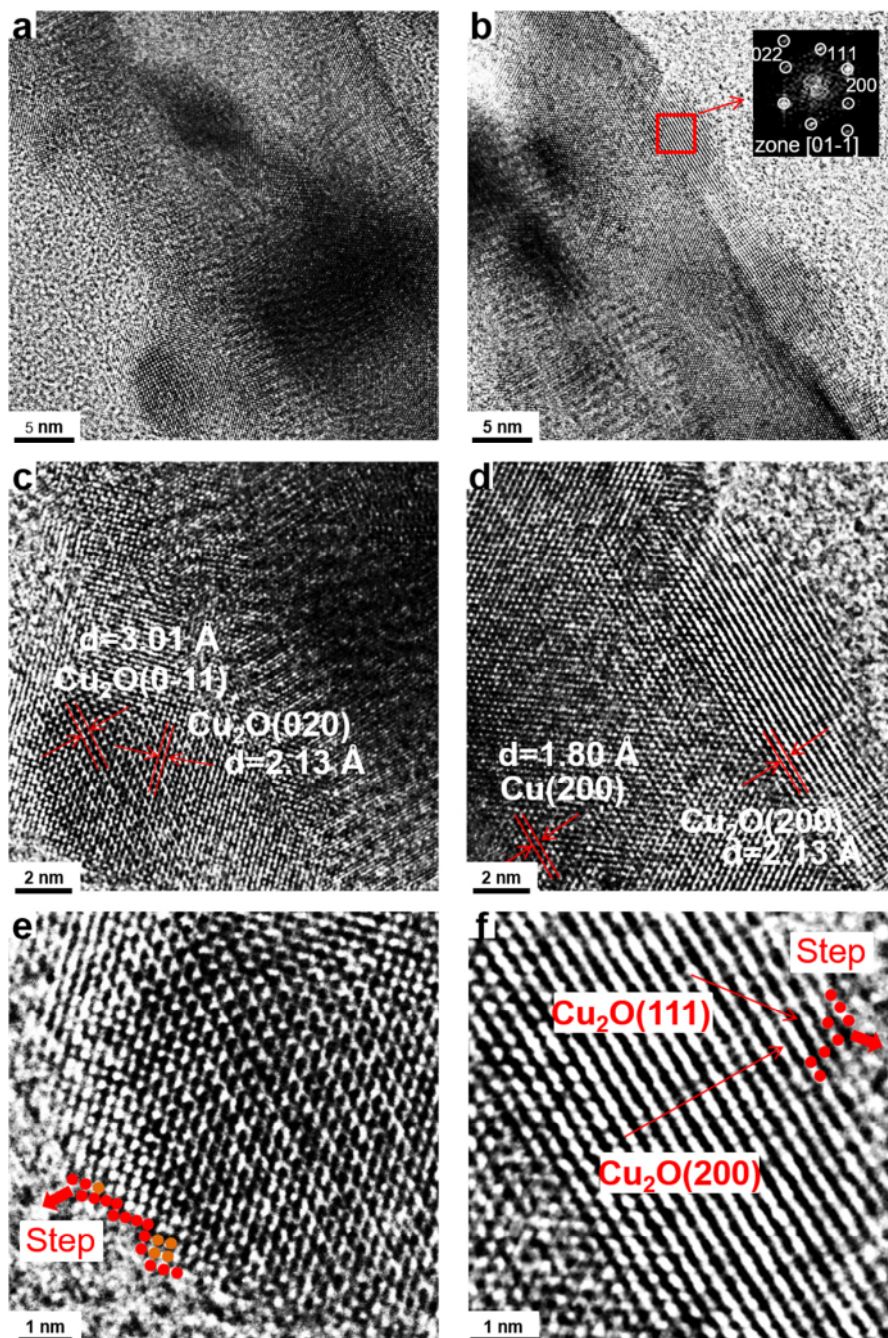
Supplementary Tables 1 to 6

Supplementary References

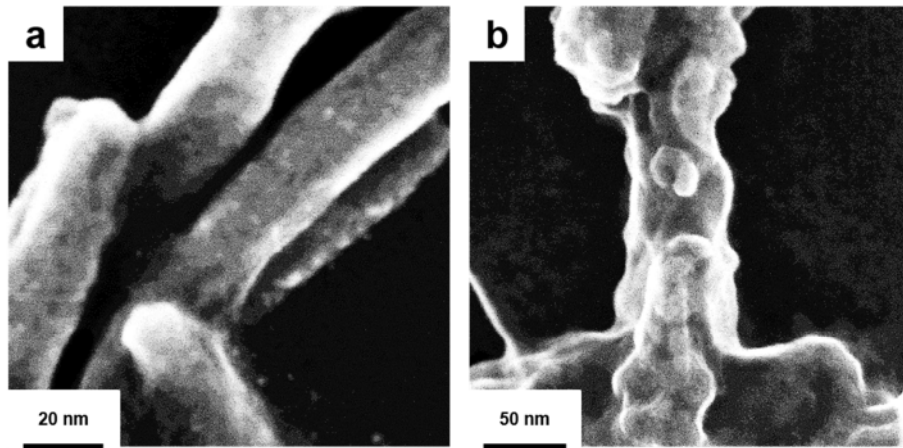
## Supplementary Figures and Tables



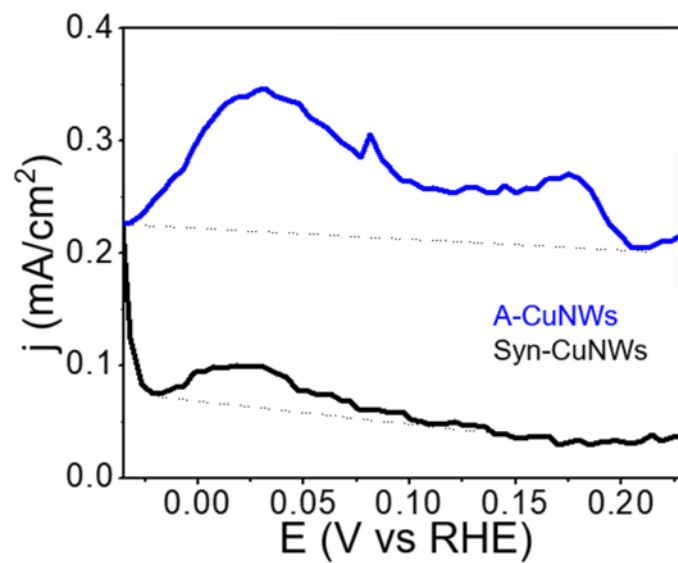
**Supplementary Fig. 1 | (a)** PXR D of Syn-CuNWs, **(b)** Size of Syn-CuNWs. The size was determined by averaging more than 100 NWs. **(c)** PXR D of polycrystalline Cu-foil.



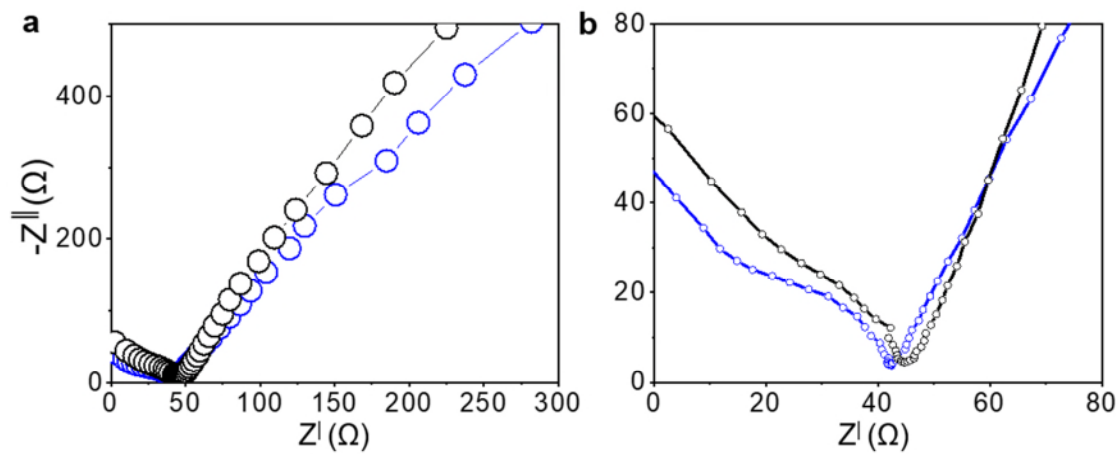
**Supplementary Fig. 2 | The highly stepped surface of A-CuNWs after the activation process, (a), (b) FFT on parts of A-CuNW, (c), (d) HRTEM images of the surface of A-CuNW, (e)  $[n(001) \times (011)]$  steps on the surface of A-CuNW, (f)  $[n(100) \times (111)]$  on the surface of A-CuNW.**



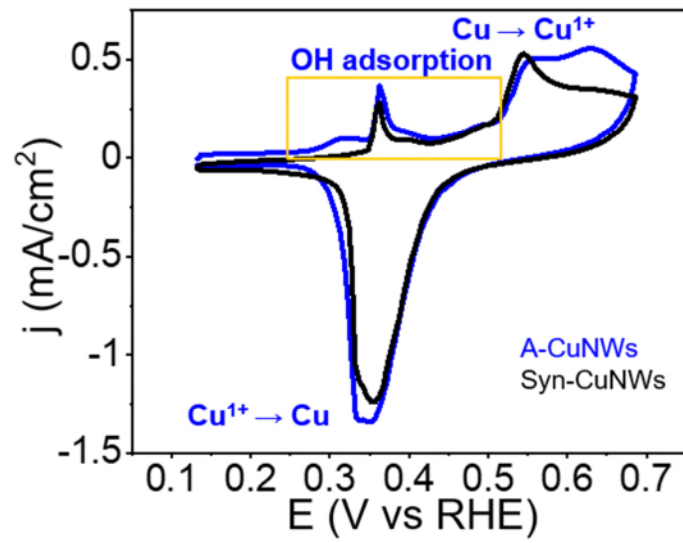
**Supplementary Fig. 3 | (a) SEI of Syn-CuNWs, (b) SEI of A-CuNWs.**



**Supplementary Fig. 4** | Pb under-potential deposition (UPD) of Syn-CuNWs (black line) and A-CuNWs (blue line) to extract ECSA measured in N<sub>2</sub>-saturated 0.1 M HClO<sub>4</sub> + 0.001 M Pb(ClO<sub>4</sub>)<sub>2</sub> solution at room temperature. The background current (dotted lines) were measured in N<sub>2</sub>-saturated 0.1 M HClO<sub>4</sub>.

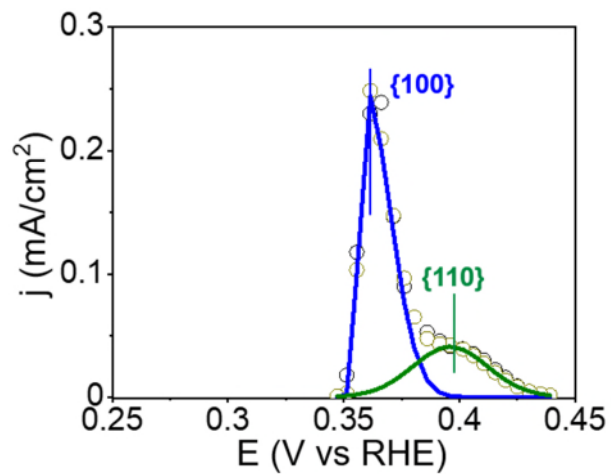


**Supplementary Fig. 5 | (a, b)** Nyquist plot of Syn-CuNWs (black) and A-CuNWs (blue).

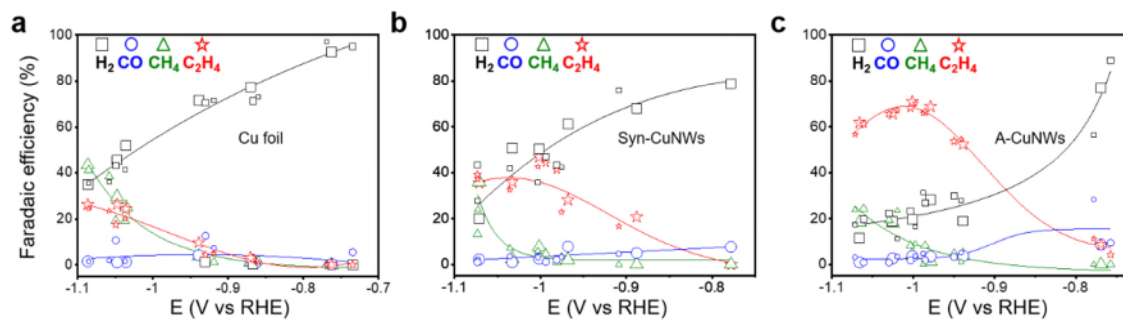


**Supplementary Fig. 6** | Redox reaction of Syn-CuNWs and A-CuNWs in 0.1 M KOH at 100 mV/s scan rate. Cu(100) at  $\sim 0.362 \text{ V}^{1-4}$ , Cu(110) at  $0.395 - 0.43 \text{ V}^{1-4}$ , Cu(111) at  $\sim 0.492 \text{ V}^{1-4}$ , and A-(hkl) (high energy steps)<sup>3,4</sup> at a negative shift from Cu(100)).

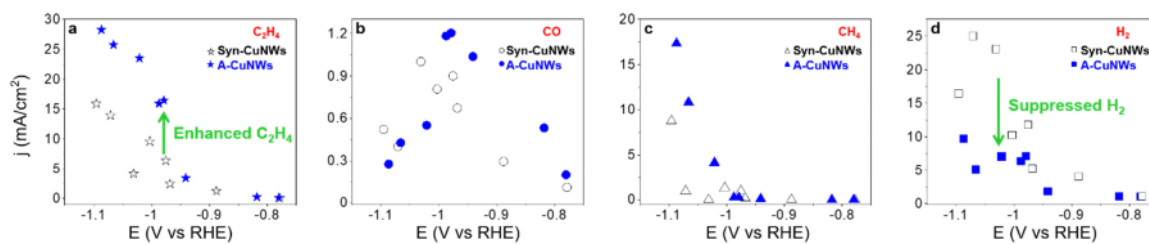




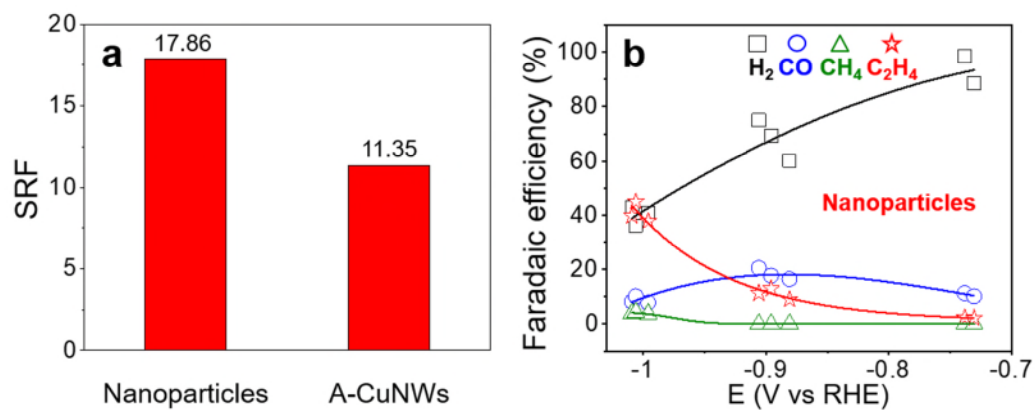
**Supplementary Fig. 7** | OH<sup>-</sup> adsorption of CuNWs after 10 min of activation. Cu(100) at ~0.362 V (blue color)<sup>1-4</sup>, Cu(110) at 0.395 – 0.43 V (green color)<sup>1-4</sup>.



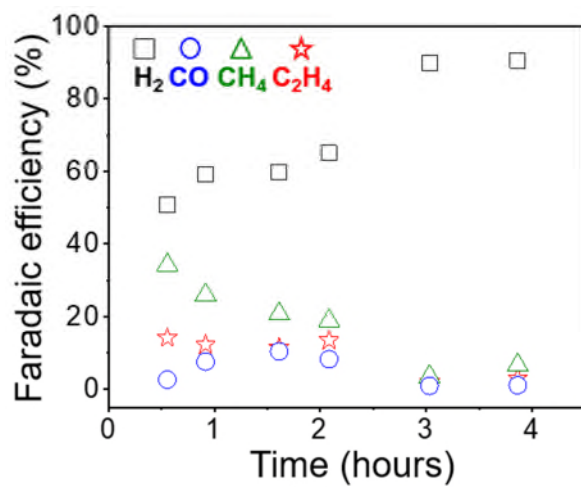
**Supplementary Fig. 8 | Electrochemical CO<sub>2</sub>RR performance from three independent measurements.** (a) FEs of Cu foil, (b) FEs of Syn-CuNW catalysts, (c) FEs of A-CuNW catalysts. Different sizes of the shape indicate different batches of CO<sub>2</sub>RR tests.



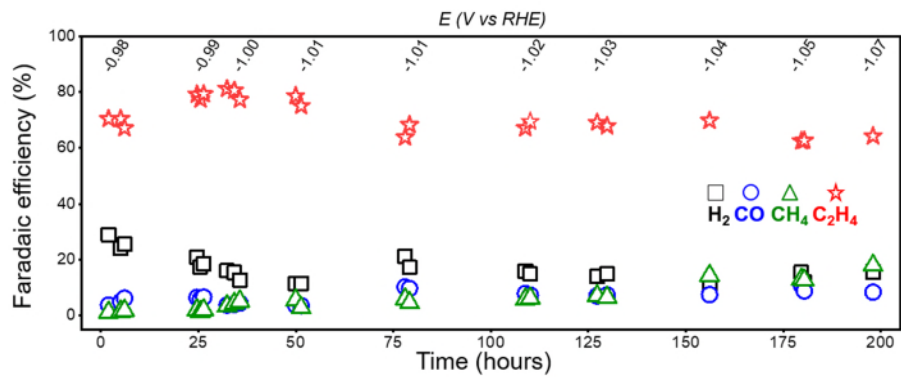
**Supplementary Fig. 9 | (a-d)** Partial current density of Syn-CuNW and A-CuNW catalysts for each product.



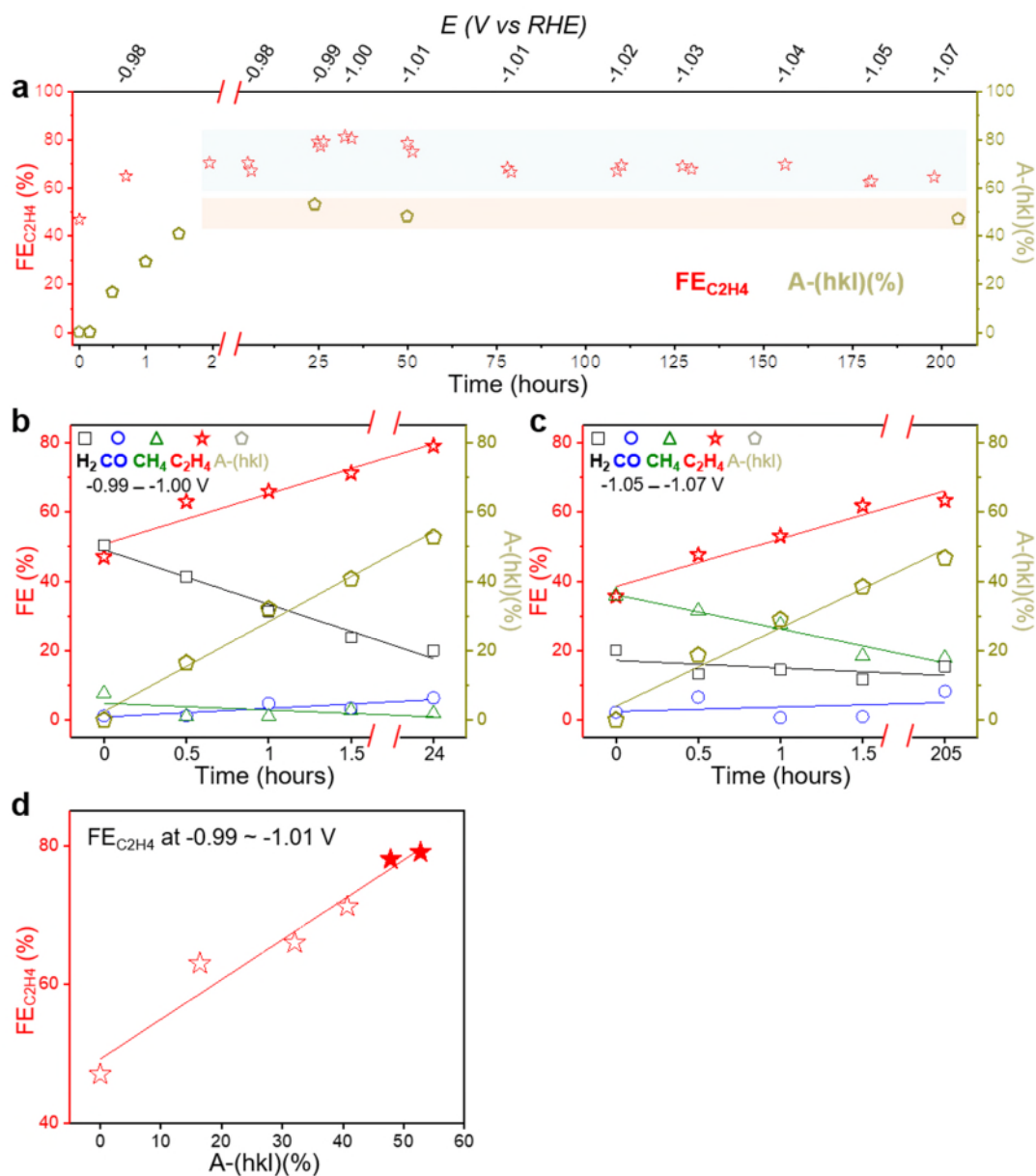
**Supplementary Fig. 10** | (a) Surface roughness factor (SRF) of commercial-Cu nanoparticles and A-CuNWs, (b) FEs for commercial-Cu nanoparticles. The SRF was calculated from CV of electrochemical double-layer from 152 to 202 mV by changing scan rates.



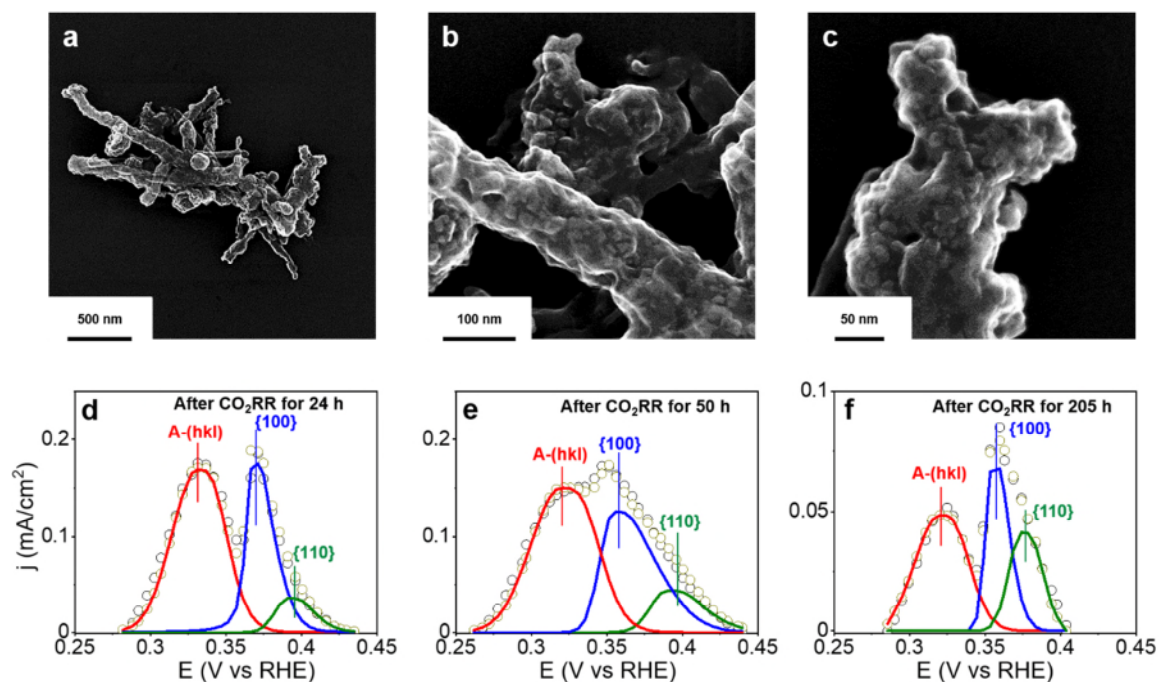
**Supplementary Fig. 11** | Stability of Cu foil at -1.07 V in 0.1 M  $\text{KCHO}_3$ .



**Supplementary Fig. 12** | Stability test of A-CuNW catalysts at potential ranging from -0.98 to -1.07 V (RHE) for 198 hours, Top axis indicates corrected potential.

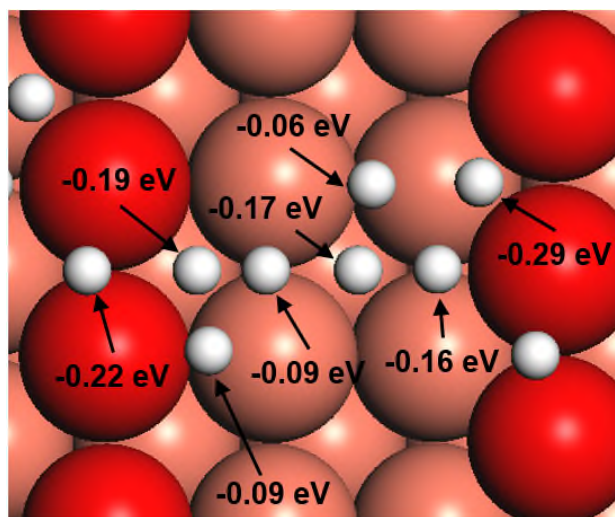


**Supplementary Fig. 13** | (a) Correlation between A-(hkl) and  $FE_{C_2H_4}$  over the long-term stability test (x-axis is broken at 2.1 h, 0 – 1.5 h correspond to activation period); (b) Correlation of both A-(hkl) and FEs with activation times at -0.99 V – -1.00 V (RHE); (c) Correlation of both A-(hkl) and FEs with activation times at -1.05 V – -1.07 V (RHE), (d) Correlation of A-(hkl) and  $FE_{C_2H_4}$  including data points from stability tests (indicated by solid red stars).



**Supplementary Fig. 14** | (a) Low magnification SEI of A-CuNW catalysts after CO<sub>2</sub>RR for 205 h, (b), (c) High magnification SEI of A-CuNW catalysts after CO<sub>2</sub>RR for 205 h. (d) OH<sup>-</sup> adsorption of CuNWs after CO<sub>2</sub>RR for 24 h, (b) after CO<sub>2</sub>RR for 50 h, (c) after CO<sub>2</sub>RR for 205 h. Cu(100) at ~0.362 V (blue color)<sup>1-4</sup>, Cu(110) at 0.395 – 0.43 V (green color)<sup>1-4</sup>, and A-(hkl) (high energy steps\_red colour)<sup>3,4</sup> at a negative shift from Cu(100).





**Supplementary Fig. 15** | The H\* binding energies of eight possible binding sites on Cu(511). Cu atoms on the step are indicated by red.

**Supplementary Table 1** | The surface portions of OH<sub>ad</sub> on each facet of all catalysts.

<b>Reaction Time</b>	<b>A-(hkl) (%)</b>	<b>Cu{100} (%)</b>	<b>Cu{110} (%)</b>
Before	0	67.49	32.50
10 min	0	73.83	26.16
30 min	17.03	62.38	20.57
1 h	28.98	57.16	13.85
1.5 h	41.12	39.50	19.37
205 h	46.82	31.58	21.58

**Supplementary Table 2** | FEs for A-CuNWs. Each point was averaged, and the standard deviation was calculated from three independent measurements.

<b>V (RHE)</b>	<b>H<sub>2</sub>%</b>	<b>CO%</b>	<b>CH<sub>4</sub>%</b>	<b>C<sub>2</sub>H<sub>4</sub>%</b>	<b>Ethanol%</b>	<b>Acetate%</b>	<b>Formate%</b>	<b>Total%</b>
-0.76 ±0.01	74.11 ±16.37	15.56 ±11.16	0	8.10 ±3.52	0	0	1.53	99.32 ±4.44
-0.94 ±0.00	25.60 ±5.74	4.05 ±0.98	3.19 ±1.87	53.62 ±1.09	0	0	1.51	87.98 ±6.61
-0.98 ±0.00	28.82 ±2.33	3.35 ±1.47	3.18 ±4.40	67.14 ±1.56	1.50	0	0.73	104.75 ±0.73
-1.00 ±0.00	19.90 ±3.39	3.05 ±1.11	7.09 ±2.71	69.79 ±1.44	2.61	1.35	0.43	104.24 ±1.55
-1.06 ±0.00	16.30 ±4.16	1.65 ±1.28	22.22 ±3.26	59.95 ±2.82	3.39	0	0.24	103.77 ±6.78

**Supplementary Table 3** | FEs for Syn-CuNWs. Each point was averaged, and the standard deviation was calculated from three independent measurements.

<b>V (RHE)</b>	<b>H<sub>2</sub>%</b>	<b>CO%</b>	<b>CH<sub>4</sub>%</b>	<b>C<sub>2</sub>H<sub>4</sub>%</b>	<b>Total%</b>
-0.89±0.01	63.59±15.01	4.25±0.97	0	22.05±6.02	89.90±9.92
-0.97±0.00	49.02±10.61	4.35±3.06	2.18±1.24	30.76±9.43	86.32±13.64
-1.00±0.00	44.39±7.62	2.23±0.98	6.09±1.49	44.65±2.20	97.38±10.09
-1.03±0.00	51.03±9.74	1.84±1.49	4.29±2.45	34.48±1.75	91.92±7.93
-1.07±0.00	30.44±11.94	1.76±0.69	24.43±11.27	37.25±1.84	93.90±3.00

**Supplementary Table 4** | FEs for Cu foil. Each point was averaged, and the standard deviation was calculated from three independent measurements

V (RHE)	H <sub>2</sub> %	CO%	CH <sub>4</sub> %	C <sub>2</sub> H <sub>4</sub> %	Ethanol%	Acetate%	Formate%	Total%
-0.75 ±0.01	94.89 ±2.26	2.04 ±2.95	0	0	0	2.08	4.79	103.81 ±3.82
-0.86 ±0.00	73.87 ±3.17	1.51 ±1.40	0.95 ±0.62	2.17 ±1.09	0	1.68	2.91	83.12 ±3.73
-0.93 ±0.00	77.87 ±11.82	6.76 ±5.17	2.42 ±1.22	6.74 ±2.73	0.31	0.46	2.39	96.96 ±8.13
-1.04 ±0.00	46.96 ±4.49	4.36 ±5.59	24.67 ±5.15	22.80 ±4.60	0.91	0.18	0.65	100.53 ±6.71
-1.07 ±0.01	35.59 ±0.62	1.67 ±0.25	40.97 ±2.49	24.81 ±1.38	0.89	0.09	0.22	104.25 ±3.03

**Supplementary Table 5** | Summary of stability of C<sub>2</sub>H<sub>4</sub> production in H-cell.

Catalysts	Applied potential V (RHE)	Stable FE <sub>C<sub>2</sub>H<sub>4</sub></sub>	Reported Duration (hours)	Electrolyte	CO <sub>2</sub> Flow rate (sccm)	Source
A-Cu NWs	-0.97 - -1.07	61 – 72%	205	0.1 M KHCO <sub>3</sub>	15	This work
A-Cu NWs	-0.98 - -1.07	64 – 79%	198	0.1 M KHCO <sub>3</sub>	15	This work
Cu Nanocube (250 – 300 nm)	- 0.95	45%	1	0.1 M KHCO <sub>3</sub>	20	(5)
Cu Nanocube (10 – 40 nm)	- 0.75	~32%	10	0.1 M KHCO <sub>3</sub>	20	(6)
Plasma treated Cu foil	- 0.9	60%	5	0.1 M KHCO <sub>3</sub>	30	(7)
CuZn nanoparticles	- 1.3	~30%	8	0.1 M KHCO <sub>3</sub>	20	(8)
Electro-redeposited Cu	- 1.2	40 – 45%	5	0.1 M KHCO <sub>3</sub>	20	(9)

**Supplementary Table 6 |** Free energy, frequency, Zero-point energy (ZPE), Enthalpy (Cv), Entropy of all states in DFT calculations.

			Energy [eV]	Frequency [cm <sup>-1</sup> ]	ZPE [eV]	Cv [eV]	TS [eV]
Cu(100)	C1	IS	-263.645	3719.04	1.606498	0.170446	0.232887
		TS	-262.971	3643.092	1.473867	0.179751	0.250323
		FS	-263.98	3716.55	1.731384	0.179365	0.249453
	C2	IS	-263.878	2697.653	0.630043	0.167448	0.253563
		TS	-263.45	2757.024	0.613232	0.13664	0.189569
		FS	-264.291	2751.579	0.674542	0.148478	0.22949
Cu(511)	C1	IS	-207.912	3711.546	1.435686	0.159278	0.221053
		TS	-207.204	3762.022	1.348848	0.189453	0.279913
		FS	-208.391	3759.418	1.583465	0.156297	0.230906
	C2	IS	-208.175	2704.296	0.641028	0.162215	0.24363
		TS	-207.709	2709.244	0.617154	0.140325	0.20639
		FS	-208.316	2813.459	0.680842	0.122072	0.179666

## Supplementary References

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